A1 INDEX
SEE NOTE 10

20
B
7.75
MIN
9.5
MAX
4.25
MAX
9.5 MAX
C
5.5 MAX
3.5 MAX
7.75
MIN
5.5 MAX
6.5 MAX
14.1
13.9
20
7 8
CAPACITOR
ZONES 4X
4X ⌓ 0.15 A
3 MAX
11.6
11.4

TOP VIEW

431X ⌓ 0.15 A
A
6
// 0.25 A
SEATING
PLANE
6
// 0.35 A
5

FLAT
PLATE
LID

22X 0.8

AC AB AA Y W V U T R P N M L K J H G F E D C B A

22X 0.8

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23

431X ⌀0.55 / 0.45
4
⌖ ⌀0.15 Ⓜ A B C
⌀0.08 Ⓜ A

BOTTOM VIEW

4X
0.6 MAX
1.5
1.28
0.5
0.3
1.3
0.9
3.3
2.48

SIDE VIEW

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
431 I/O FC BGA,
20 X 20 PKG, 0.8 MM PITCH,
WITH LID AND CAP ZONES

DOCUMENT NO: 98ARE10549D REV: D

STANDARD: NON-JEDEC

SOT1626-1 17 DEC 2015

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. FEATURES ARE SYMMETRICAL ABOUT THE PACKAGE CENTER LINES UNLESS DIMENSIONED OTHERWISE.

4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

7. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

8. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

9. FC CBGA (CERAMIC) PACKAGE CODE: 5238
   FC PBGA (PLASTIC) PACKAGE CODE: 5263

10. PIN 1 INDICATOR CAN BE IN THE FORM OF NUMBER 1 MARKING OR AN "L" SHAPE MARKING

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